

IN THE CLAIMS:

Claim 1 (currently amended): A low resistance value resistor comprising:  
a resistor body comprised by a resistive alloy, the body having a thickness of 50-2000 $\mu$ m;

at least two electrodes, comprised by metal strips of flat tetragonal shape having a high electrical conductivity, each of said metal strips having a length equal with a width of said resistor body, and affixed on one surface of the resistor body separately wherein a diffusion layer is formed at an interface between the resistor body and the metal strip or in an interior of the resistor body under the metal strip;

a straight and uniform current path formed in the resistor body between said electrodes;

a fused solder layer only on each surface of the electrodes;

an insulation layer covering a portion of said surface of the resistor body defined between said electrodes; and

another insulation layer entirely covering another surface of said resistor body opposite to the surface of the resistor body having the electrodes.

Claims 2-20 (Cancelled).

Claim 21 (Currently amended): A low resistance value resistor according to claim 1, wherein said further comprising a fused solder layer having a thickness of 2-10  $\mu$ m on each surface of the electrodes, said fused solder layer being formed by fused solder

material of Sn:Pb=9:1 (weight %) or lead-free solder material.

Claim 22 (Cancelled).

Claim 23 (Previously added): A low resistance value resistor according to claim 1, wherein a thickness of the electrodes is 10-500  $\mu\text{m}$ .

Claim 24 (Previously added): A low resistance value resistor according to claim 1, wherein a thickness of the electrodes is not less than a 1/10 fraction of a thickness of the resistor body.

Claim 25 (Previously added): A low resistance value resistor according to claim 1, wherein said resistor body comprises Cu-Ni alloys, Ni-Cr alloys, Fe-Cr alloys, Mn-Cu-Ni alloys, Pt-Pd-Ag alloys, Au-Ag alloys, or Au-Pt-Ag alloys.

Claim 26 (Previously added): A low-resistance value resistor according to claim 1, wherein said electrode comprises copper.

Claim 27 (Previously added): A low resistance value resistor according to claim 1, wherein a resistivity of the electrode comprised by the high electrical conductivity metal strip is not less than a 1/150 fraction and not more than a 1/2 fraction of a resistivity of the

resistor body.

Claim 28 (Currently amended): A low resistance value resistor according to claim 1, wherein a resistance value of the resistor is adjusted by varying at least a thickness or a width of the resistor body.

Claim 29-30 (Cancelled).

Claim 31 (Previously amended): A low resistance value resistor according to claim 1, wherein said insulation layer comprises one of epoxy resin, an acrylic resin, a fluorine resin, a phenol resin, a silicone resin, and a polyimide resin.

Claim 32 (Previously amended): A low resistance value resistor according to claim 1, wherein said another insulation layer comprises one of epoxy resin, an acrylic resin, a fluorine resin, a phenol resin, a silicone resin, and a polyimide resin.

Claim 33 (Currently amended): A low resistance value resistor comprising:  
a resistor body comprised by a resistive alloy, the body having a thickness of 50-  
2000  $\mu$ m;

at least two electrodes, comprised by metal strips of flat tetragonal shape having a high electrical conductivity, each of said metal strips having a length equal with a width of

said resistor body, and affixed on one surface of the resistor body separately wherein a diffusion layer[[s]] is formed at an interface between the resistor body and the metal strip or in an interior of the resistor body under the metal strip;

two bonding electrodes of flat tetragonal shape disposed at both ends of a surface of the resistor body opposite to the surface having the electrodes;

a fused solder layer only on each surface of the electrodes; and

a straight and uniform current path formed in the resistor body between said at least two electrodes.

Claim 34 (Previously added): A low resistance value resistor according to claim 33, wherein bonding positions are provided on an area located at lateral outer side of respective center lines of the bonding electrodes.

Claim 35 (Previously added): A low resistance value resistor according to claim 33, wherein material of said bonding electrodes includes nickel, aluminum, or gold.

Claim 36 (Currently amended): A low resistance value resistor according to claim 33, wherein a said fused solder layer having has a thickness of 2-10  $\mu\text{m}$  ~~is provided on each surface of the electrodes.~~

Claim 37 (Previously added): A low resistance value resistor according to claim 36,

wherein said fused solder layer is formed by fused solder material of Sn:Pb=9:1 (weight %) or lead-free solder material.

Claim 38 (Cancelled).

Claim 39 (Previously added): A low resistance value resistor according to claim 33, wherein a thickness of the electrodes is 10-500  $\mu\text{m}$ .

Claim 40 (Previously added): A low resistance value resistor according to claim 33, wherein a thickness of the electrodes is not less than a 1/10 fraction of a thickness of the resistor body.

Claim 41 (Previously added): A low resistance value resistor according to claim 33, wherein said resistor body comprises Cu-Ni alloys, Ni-Cr alloys, Fe-Cr alloys, Mn-Cu-Ni alloys, Pt-Pd-Ag alloys, Au-Ag alloys, or Au-Pt-Ag alloys.

Claim 42 (Previously added): A low-resistance value resistor according to claim 33, wherein said electrode comprises copper.

Claim 43 (Previously added): A low resistance value resistor according to claim 33, wherein a resistivity of the electrode comprised by the high electrical conductivity metal

strip is not less than a 1/150 fraction and not more than a 1/2 fraction of a resistivity of the resistor body.

Claim 44 (Previously added): A low resistance value resistor according to claim 33, wherein a resistance value of the resistor is adjusted by varying at least a thickness of the resistor body.

Claims 45-56 (Cancelled).

Claims 57-59 (Withdrawn).